



BSI Standards Publication

## Connectors for electrical and electronic equipment — Tests and measurements

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Part 27-200: Additional specifications for signal integrity tests up to 2 000 MHz on IEC 60603-7 series connectors — Tests 27a to 27g

## National foreword

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**Connectors for electrical and electronic equipment – Tests and measurements –  
Part 27-200: Additional specifications for signal integrity tests up to 2 000 MHz on  
IEC 60603-7 series connectors – Tests 27a to 27g**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**CONNECTORS FOR ELECTRICAL AND ELECTRONIC EQUIPMENT –  
TESTS AND MEASUREMENTS –****Part 27-200: Additional specifications for signal integrity tests up to  
2 000 MHz on IEC 60603-7 series connectors – Tests 27a to 27g**

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IEC PAS 60512-27-200 has been processed by subcommittee 48B: Electrical connectors, of IEC technical committee 48: Electrical connectors and mechanical structures for electrical and electronic equipment.

The text of this PAS is based on the following document:

This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document

| Draft PAS     | Report on voting |
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Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

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## CONNECTORS FOR ELECTRICAL AND ELECTRONIC EQUIPMENT – TESTS AND MEASUREMENTS –

### Part 27-200: Additional specifications for signal integrity tests up to 2 000 MHz on IEC 60603-7 series connectors – Tests 27a to 27g

#### 1 Scope

This part of IEC 60512 covers additional, supplemental specifications for signal integrity and transmission performance test methods of IEC 60512-27-100, for connectors using de-embedded crosstalk measurements, which are specified in respective parts of IEC 60603-7 standards for connecting hardware applications up to 2 000 MHz.

These additional specifications are also applicable for testing the related lower frequency connectors. However, the test methodology specified in the detail specification for any given connector remains the reference conformance test for that connector.

Test procedures of IEC 60512-27-100 affected by these supplemental methods and procedures are:

- insertion loss, test 27a;
- return loss, test 27b;
- near-end crosstalk (NEXT) test 27c;
- far-end crosstalk (FEXT), test 27d;
- transverse conversion loss (TCL), test 27f;
- transverse conversion transfer loss (TCTL), test 27g.

Other test procedures referenced here are:

- transfer impedance ( $Z_T$ ), see test procedures in IEC 62153-4-6 or IEC 62153-4-7.
- for coupling attenuation ( $a_C$ ), see test procedures in IEC 62153-4-7 or IEC 62153-4-12.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-581, *International Electrotechnical Vocabulary (IEV) – Part 581: Electromechanical components for electronic equipment*

IEC 60512-1, *Connectors for electronic equipment – Tests and measurements – Part 1: General*

IEC 60512-26-100, *Connectors for electronic equipment – Tests and measurements – Part 26-100: Measurement setup, test and reference arrangement and measurements for connectors according to IEC 60603-7 – Tests 26a to 26g*

IEC 60512-27-100, *Connectors for electronic equipment – Tests and measurements – Part 27-100: Signal integrity tests up to 500 MHz on 60603-7 series connectors – Tests 27a to 27g*